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## PATENT ABSTRACTS OF JAPAN

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### (54) MULTILAYER CIRCUIT BOARD AND MANUFACTURE THEREOF

(57) Abstract:

**PURPOSE:** To make the land of an upper conductor small in size so as to enable a conductor pattern to be improved in density by a method wherein a through-hole is formed into a stepped shape provided with a flat plane located at the halfway point in a thicknesswise direction of the polyimide layer and extending sideways, and the joint land of the upper conductor connected to a lower conductor is provided onto the flat plane concerned.

**CONSTITUTION:** A through-hole 14 is provided to a polyimide layer 13 in such manner that it is formed into a stepped shape provided with a flat plane 14a located at its halfway point in a thicknesswise direction extending sideways, and the joint land 15c of an upper conductor 15 connected to a lower conductor 12 is provided onto the flat plane 14a concerned. That is, the joint land of the upper conductor 15 connected to the lower conductor 12 is formed closer to the lower conductor 12 than a conventional one. Therefore, a land can be formed smaller in diameter. By this setup, the upper conductor 15 can be formed high in density, so that a multilayered circuit board can be improved in degree of integration.

